

In the Claims:

Please cancel claims 1, 7, 9 without prejudice or disclaimer, amend claims 2-6 and 8 , and add new claim 13 as follows:

1. (Cancelled)
2. (Currently Amended) ~~A~~ The high frequency circuit module according to claim 1, wherein RF circuit parts are mounted on both sides of a multilayer dielectric substrate, transmission lines connecting said RF circuit parts on both sides are constructed by a group of vias having a periodical structure or vias having a coaxial structure extended in a direction perpendicular to the face of said multilayer dielectric substrate, and said via group of vias having the periodical structure is constructed so that a plurality of vias are distributed around a center conductor at an interval which is equal to or smaller than 1/4 of wavelength of a signal of said transmission line.
3. (Currently Amended) ~~A~~ The high frequency circuit module according to claim 1 comprising:
a multilayer dielectric substrate having a first and a second dielectric substrates each of which has RF circuit parts mounted on one side thereof, and at least one third dielectric substrate provided between the first and second dielectric substrates, and a transmission line constructed by a via having a coaxial structure connecting said RF circuit parts of the first and second dielectric substrates in a direction perpendicular to the face of said multilayer dielectric substrate.
wherein said via having the a coaxial structure is formed by a center conductor and a cylindrical conductor surrounding said center conductor and connected to a plurality of grounding conductive layers provided in said multilayer dielectric substrate, each of said grounding conductive layers is connected to both sides of the cylindrical conductor and has a circular radial gap from an inner land connected to said center conductor, and said circular radial gap is smaller than ¼ of a wavelength of a high frequency signal to be transmitted through the transmission line.
4. (Currently Amended) The high frequency circuit module according to claim 4~~3~~, wherein a high frequency circuit part provided on one of the faces of said multilayer second dielectric substrate is an antenna.

5. (Currently Amended) The high frequency circuit module according to claim 43, wherein said multilayer dielectric substrate includes three or more dielectric substrate layers, a microstrip transmission line of a millimeter wave circuit part is formed by the first dielectric substrate, a pattern of a surface metallic layer on one surface of the a-first dielectric substrate layer and a metallic layer provided between the first dielectric substrate layer and said third dielectric substrate second layers, and a metallic layer formed in another intermediate layer in said dielectric substrate has a transmission line to which an intermediate transmitting a low frequency signal and power is formed by another metallic layer provided in the multilayer dielectric substrate generated by said millimeter wave circuit part is connected.

6. (Currently Amended) The high frequency circuit module according to claim 54, comprising wherein said second dielectric substrate is made of a both-sided two-layered dielectric substrate having permittivity being lower than permittivity of a fourth dielectric substrate and having a size larger than said fourth dielectric substrate in which a final layer on the side opposite to the first layer of said multilayer dielectric substrate is larger than the other plurality of dielectric substrates of said multilayer dielectric substrate, wherein a metallic layer of an antenna pattern is formed on one of the faces of the final layer, and a support plate is formed in the portion where said [other] fourth dielectric substrates are is not stacked on the other a face of said final layer the second dielectric substrate opposite to the face provided with the antenna.

7. (Cancelled)

8. (Currently Amended) The high frequency circuit module according to claim 5, wherein said multilayer dielectric substrate is constructed so that the lines for intermediate frequency signal and the high frequency signal are disposed between said grounding metallic layers and do not cross a sealing portion of said multilayer dielectric substrate with said a hermetic cap is mounted on a sealing pattern formed on the surface of said first dielectric substrate to cover the high frequency circuit parts.

9. (Cancelled)
10. (Original) An automotive radar module,
wherein an antenna metallic pattern is formed on one of faces of a multilayer dielectric substrate,
RF circuit parts including an oscillation circuit, a power amplifier for amplifying a part of an output of said oscillation circuit and supplying the amplified output to said antenna, and a mixer for mixing a signal from said antenna metallic pattern with a signal of the oscillation circuit are formed on the other face of said multilayer dielectric substrate, and
a transmission line for connecting said antenna metallic pattern and said RF circuit parts is constructed by a group of vias including a periodical structure or vias having a coaxial structure provided in the direction perpendicular to faces of said multilayer dielectric substrate.
11. (Original) The automotive radar module according to claim 10, wherein the group of vias including said periodical structure is constructed so that the vias are distributed around a center conductor at an interval which is equal to or smaller than 1/4 of a wavelength of a signal of said transmission line.
12. (Original) The automotive radar module according to claim 10, wherein said via having the coaxial structure is formed by a center conductor and a cylindrical conductor surrounding said center conductor and connected between grounding conductive layers provided in said multilayer dielectric substrate.
13. (New) The high frequency circuit module according to claim 2, wherein the RF parts provided on one face of said second dielectric substrate is an antenna.